



# Product Change Notification

**Change Notification #:** PCN115116-00  
**Change Title:** Intel® Server Chassis R2312WTTYSR, PC115116-00, Product Design, Top screw removal, Change dimension on PCIe\* riser bracket holes, Hot Swap Back Plane Sheet Metal Locator Tab Modification

**Date of Publication:** November 22, 2016

## Key Characteristics of the Change:

Product Design

## Forecasted Key Milestones:

|   |                  |
|---|------------------|
| <b>Date Customer Must be Ready to Receive Post-Conversion Material:</b> | December 7, 2016 |
|---|------------------|

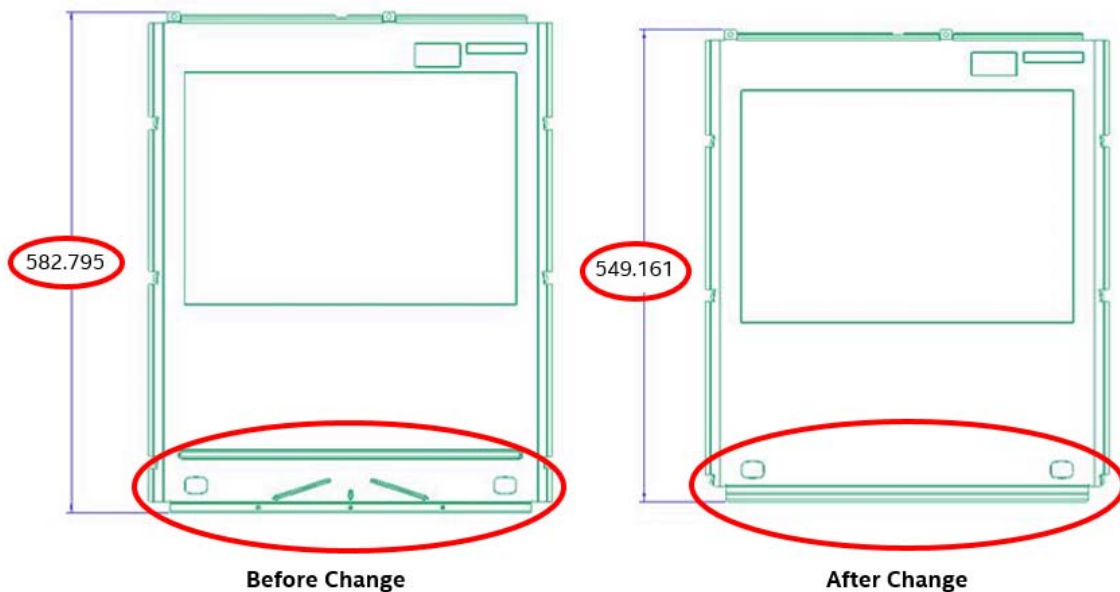
*Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.*

## Description of Change to the Customer:

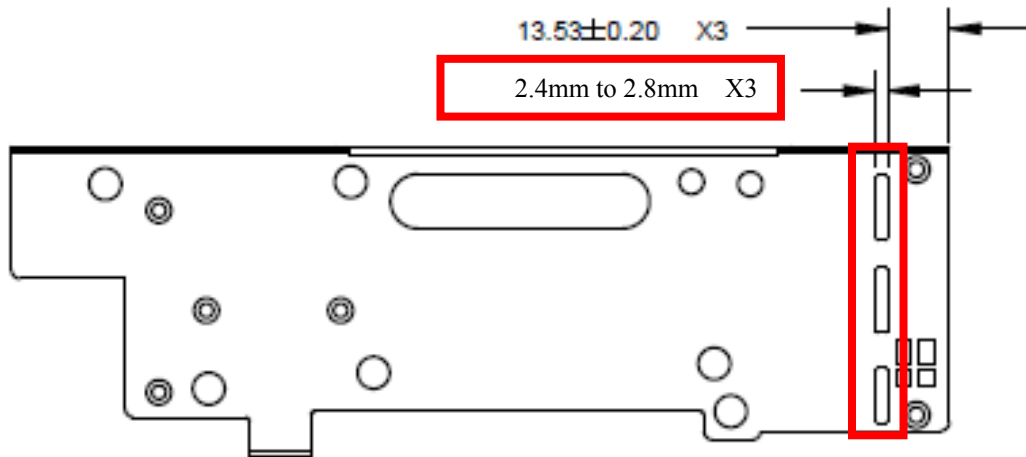
Intel is implementing the following changes on the Intel® Server Chassis R2312WTTYSR:

Next changes will be applied to the Intel® Server Systems R2312WTTYSR and Intel® Server Chassis R2312WTXXX:

1. remove three screws from the top cover
2. reduce length of the top cover



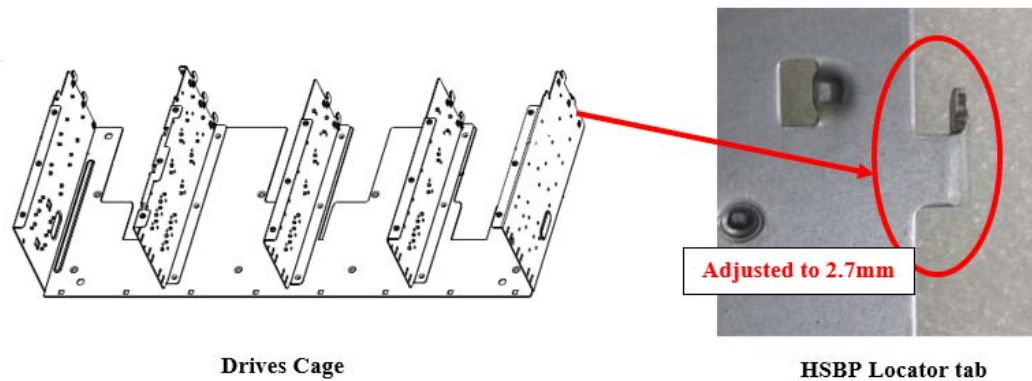
3. The width of the holes in the Peripheral Component Interconnect Express (PCIe) Riser bracket change from 2.4mm to 2.8mm. Please see image below for details:



**Image 1.** PCIe\* bracket holes

This change will eliminate any difficulty with customers installing PCIe cards in riser 2 and riser 3 on opposing PCIe slots.

4. The sheet metal of the locator at the bottom tab of the hot swap back plane (HSBP) that is in the right side will be modified to ensure gap of 2.7mm. This modification is needed to provide reliable engagement between the drive and the backplane connectors. Please see additional information in the TA-1107 available at: <http://www.intel.com/content/www/us/en/support/server-products/000022064.html?wapkw=ta-1107>



**Drives Cage**

**HSBP Locator tab**

### **Customer Impact of Change and Recommended Action:**

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications. For that reason Intel recommends that the customer perform a standard level of evaluation.

Please contact your local Intel Field Sales Representative if you have any further questions about these changes.

### **Products Affected / Intel Ordering Codes:**

| <b>Product Code</b> | <b>MM#</b> | <b>Pre Change TA</b> | <b>Post Change TA</b> |
|---------------------|------------|----------------------|-----------------------|
| R2312WTTYSR         | 951229     | J11495-006           | J11495-007            |

### **PCN Revision History:**

|                          |                         |                          |
|--------------------------|-------------------------|--------------------------|
| <b>Date of Revision:</b> | <b>Revision Number:</b> | <b>Reason:</b>           |
| November 22, 2016        | 00                      | Originally Published PCN |



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## PCN 115116-00

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**Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

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